SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE **SAME**

Appl. No. : 10/710,399

Confirmation No. 4398

Applicant : Min-Jer Lin

Filed

: July 8, 2004

TC/A.U. : 2818

Examiner : DAO H. NGUYEN

Docket No.

: LKSP0027USA

Customer No. : 27765

Commissioner for Patents

P.O. Box 1450

Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office action of December 14, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of 10 this paper.

Remarks/Arguments begin on page 9 of this paper.